

Epotack®

Product Name	ZC-210
Product Category	Potting Resin for Semiconductors, One Component Type Resin
Usage	Semiconductor Modules, General Modules
Function	One Component, Low Stress, Low Curing Shrinkage, Low Warpage

As supplied

(Typical Value)

Item	Condition	Unit	
Appearance	visual	—	Black liquid
Viscosity	25°C 1rpm	Pa·s	780
	25°C 2rpm	Pa·s	550
	25°C 5rpm	Pa·s	360
	25°C 10rpm	Pa·s	260
TI Value	0.5/5rpm 25°C	—	3.0
Specific Gravity	Buoyancy method	—	1.84

Standard Curing Condition 100°C x 1 hour + 150°C x 3 hours

As cured

Item	Condition	Unit	Typical Value
Hardness	JIS K 7215 25°C	Shore D	96
Curing Shrinkage	120×10×10(mm)	%	0.23
Glass Transition Temperature	JIS K 7197 TMA	°C	175
Coefficient of Thermal Expansion	below Tg	10 ⁻⁵ /°C	1.5
	above Tg	10 ⁻⁵ /°C	8.0
Volume Resistivity	JIS K 6911 25°C	Ω·cm	7.2 x 10 ¹⁶
	PCT 24hrs	Ω·cm	2.9 x 10 ¹³
Shear Adhesive Strength	JIS K 6850 25°C Iron	MPa	7
	JIS K 6850 25°C Aluminum	MPa	11
	JIS K 6850 25°C Copper	MPa	14
	JIS K 6850 25°C Alumina	MPa	6

The above values are typical and not specification



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